

Build Up HDI (Standard)

HDI08_2+4(6b)+2_1,60_35_engl

8 - Layers

Core: 0,51 mm Cu 35/35 μm



WE-Articel No.:

2 + 4(6B) + 2

Customer:

layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[μm]	[μm]
	TOP/VS		Foil	12 μm 1)		12	
					1 x 1080	60	
	2		Foil	9 μm		30	
					1 x 1080	60	
	3			35 μm		33	
			0,510 mm			510	
	4			35 μm		33	
					2 x 1080	124	
	5			35 μm		33	
			0,510 mm			510	
	6			35 μm		33	
					1 x 1080	60	
	7		Foil	9 μm		30	
					1 x 1080	60	
	BOT/RS		Foil	12 μm 1)		12	

1) copper thickness outer layers: appr. 55 μm

total material thickness: 1600

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	1,60	+/-	0,13	mm		Date:	Engineer:
thickness with electro plated Cu:	1,69	+/-	0,16	mm			
total thickness with soldermask	1,75	+/-	0,18	mm			
customer requirement		+/-		mm	point:		

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